



Title of Change:	Gold wire to bare copper wire conversion for Zener and ESD Protection devices assembled in ON Semiconductor Leshan facility.							
Proposed first ship date:	30 April 2019							
Contact information:	Contact your local ON Semiconductor Sales Office or <Jim.Peng@onsemi.com>							
Samples:	Samples should be available after completion of qualification. Contact your local ON Semiconductor Sales Office.							
Type of notification:	<p>This is an Initial Product/Process Change Notification (IPCN) sent to customers. IPCNs are issued at least 30 days prior to the issuance of the Final Change Notice (FPCN). An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.</p> <p>The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>.</p>							
Change Part Identification:	Products assembled with 0.8 mils bare copper wire from ON Semiconductor Leshan facility will have a Finish Goods Date Code of May, 2019 or later.							
Change category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____							
Change Sub-Category(s):	<input type="checkbox"/> Manufacturing Site Change/Addition <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____							
Sites Affected:	ON Semiconductor Sites: ON Leshan, China	External Foundry/Subcon Sites: None						
Description and Purpose:	<table border="1"> <thead> <tr> <th></th> <th style="background-color: #92d050;">Before Change Description</th> <th style="background-color: #92d050;">After Change Description</th> </tr> </thead> <tbody> <tr> <td>Wire</td> <td>0.8 mils gold wire</td> <td>0.8 mils bare copper wire</td> </tr> </tbody> </table>			Before Change Description	After Change Description	Wire	0.8 mils gold wire	0.8 mils bare copper wire
	Before Change Description	After Change Description						
Wire	0.8 mils gold wire	0.8 mils bare copper wire						



Qualification Plan:

Test	Specification	Condition	Interval
PC	JESD22-A113	MSL 1 @ 260 °C	Before TC, UHAST, HAST, IOL
UHAST	JESD22 A118	Ta=130C, 85% RH, no bias, 96 hrs	96 hrs
TC	JESD22-A104	Ta= - 65°C to +150°C	2000 cyc
HAST	JESD22 A110	130C/85%RH, 80% rated V or 42V max, 192 hours.	192 hrs
IOL	MIL-STD-750 (M1037)	Ta=+25°C, delta Tj=100°C, On/off = 2 min	30000 cyc
HTRB	MIL-STD750-1	Tj= max, V=100% rated V, 1008 Hrs	1008 hrs
HTSL	JEDS22- A103	Temp.=150°C,no bias,2016hours	2016 hrs
RSH	JESD22- B106	Ta = 265C, 10 sec	-

Estimated date for qualification completion: 20 April 2018

List of Affected Standard Parts:

Part Number	Qualification Vehicle
ESDR0502BT1G	SZESDR0502BT1G
MM5Z3V9T1G	SZMM5Z47VT1G
ESD7951ST5G	SESD9L3.3ST5G
ESD9D5.0ST5G	SESD9L3.3ST5G

Appendix A: Changed Products

Product	Customer Part Number	Qualification Vehicle
ESD7951ST5G		SESD9L3.3ST5G
ESD9D5.0ST5G		SESD9L3.3ST5G
ESDR0502BT1G		SZESDR0502BT1G